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10. SILKSCREEN DATE CODE, LOT CODE, AND LOGO APPROX. WHERE SHOWN.
9. ALL VIA HOLES 0.016 SHALL BE TENTED.
8. PLATED HOLES SHALL HAVE PLATING THICKNESS GREATER THAN 0.0012.
7. FINISH: ALL EXPOSED CONDUCTIVE SURFACES TO BE SILVER AFTER APPLICATION OF SOLDER MASK.
6. DIELECTRIC MATERIAL IS FR-4 Tg > 130
5. COPPER WEIGHT IS 2 OZ.
4. NUMBER OF LAYERS IS 4
3. PCB THICKNESS IS 0.062
2. BOARD DESIGNED IAW IPC-2221, CLASS 2.
1. DIMENSIONS IN INCHES.

DESIGN BY CHRIS ARNTZEN

RESTEP

Sheet:

File: OffLine.kicad\_pcb

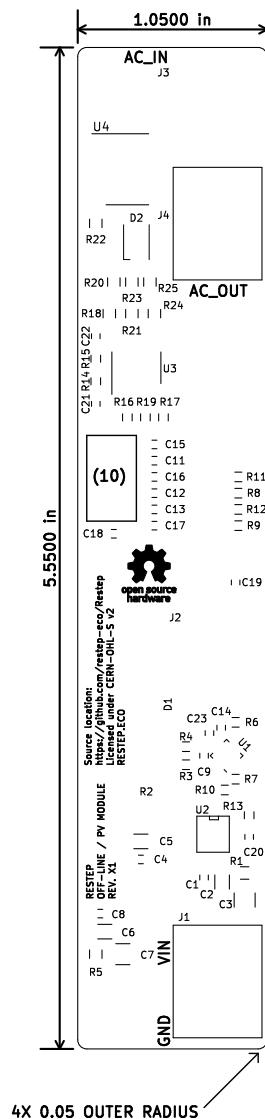
**Title: OFF-LINE POWER SUPPLY / PV MODULE PCB**

Size: A4 Date: 8/11/18

Rev: X1

KiCad E.D.A. kicad 4.0.7

Id: 1/1



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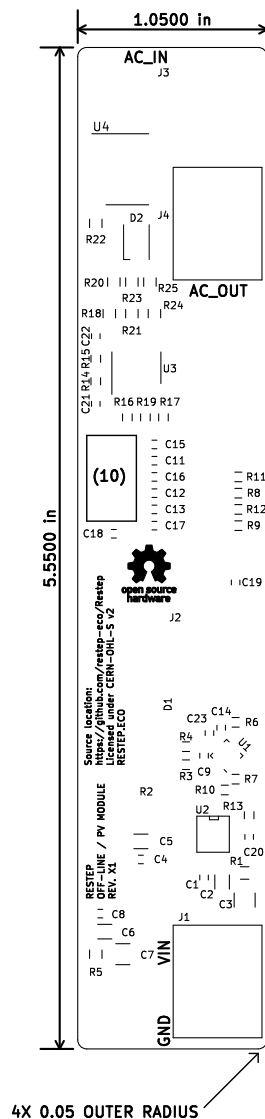
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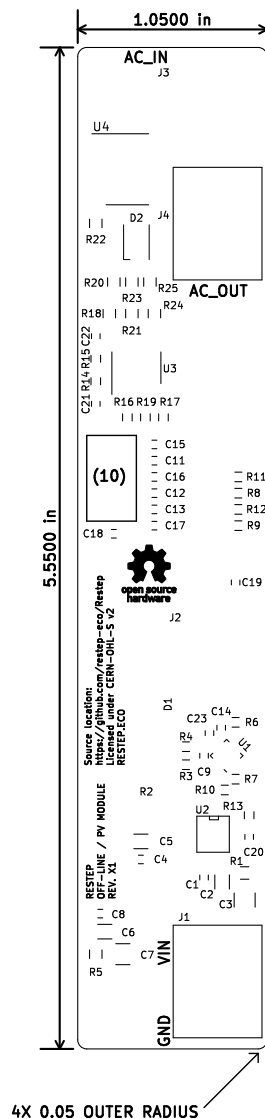
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